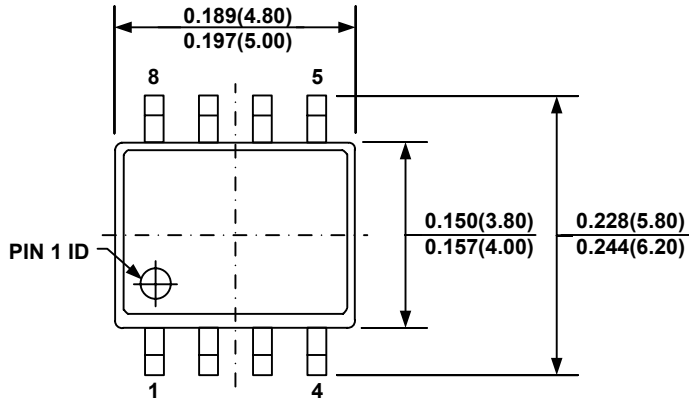
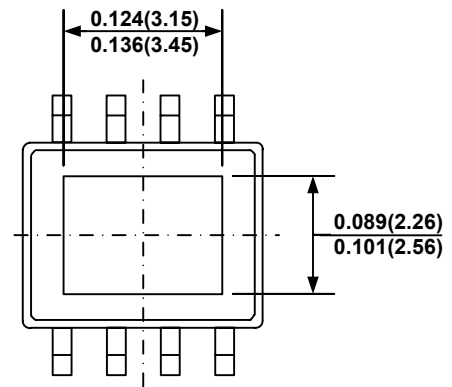


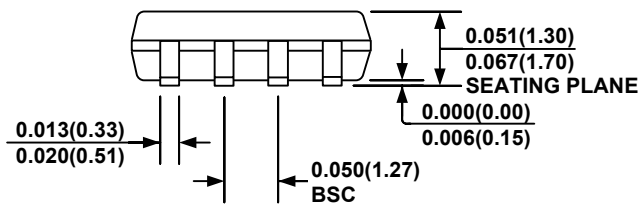
PACKAGE OUTLINE DRAWING FOR 8-SOIC w/ EXPOSED PAD MF-PO-D-0018, revision 1.0



TOP VIEW

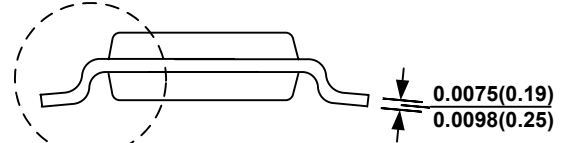


BOTTOM VIEW

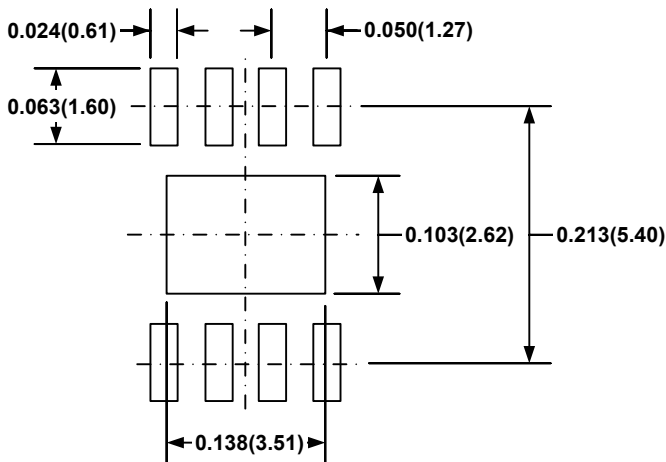


FRONT VIEW

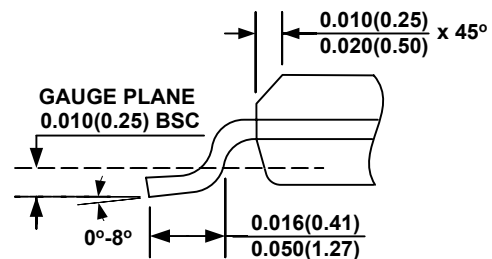
SEE DETAIL "A"



SIDE VIEW



RECOMMENDED LAND PATTERN



DETAIL "A"

NOTE:

- 1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
- 2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) DRAWING CONFORMS TO JEDEC MS-012, VARIATION BA.
- 6) DRAWING IS NOT TO SCALE.